



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD040N03L G		<b>Issued</b>		19. January 2018		
<b>MA#</b>		MA001662062						
<b>Package</b>		PG-TO252-3-311		<b>Weight*</b>		317.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.734	0.55	0.55	5464	5464
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		135	
	non noble metal	iron	7439-89-6	0.143	0.05		451	
	non noble metal	copper	7440-50-8	143.098	45.08	45.14	450807	451393
	non noble metal	aluminium	7429-90-5	3.467	1.09	1.09	10921	10921
wire	non noble metal	aluminium	7429-90-5	3.467	1.09	1.09	10921	10921
encapsulation	organic material	carbon black	1333-86-4	0.317	0.10		999	
	plastics	epoxy resin	-	19.140	6.03		60297	
	inorganic material	silicondioxide	60676-86-0	124.668	39.27	45.40	392747	454043
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11782	11782
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	272	273
solder	non noble metal	tin	7440-31-5	0.036	0.01		113	
	noble metal	silver	7440-22-4	0.045	0.01		141	
	non noble metal	lead	7439-92-1	1.707	0.54	0.56	5377	5631
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.04	6.05	60415	60493
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com